CLAIMS

1. An Al bonding wire consisting of Sc, at least one of Y, La, Ce, Pr and Nd, and a balance, wherein

the Al bonding wire comprises 0.01 to 1% by mass of Sc and further 0.01 to 0.1% by mass in total of at least one or more of Y, La, Ce, Pr and Nd, with the balance comprising Al and inevitable impurities.

2. The Al bonding wire according to claim 1, wherein an average crystal grain size in a cross-section perpendicular to a wire longitudinal direction is 0.1 to 50 μm.

3. The Al bonding wire according to claim 1 or 2, wherein in a cross-section perpendicular to a wire longitudinal direction, an area ratio of a crystal having a crystal orientation <111> angled at 15 degrees or less to a wire longitudinal direction is 30 to 90%.

4. The Al bonding wire according to any one of claims 1 to 3, wherein the Vickers hardness of the wire falls within a range from Hv20 to 40.

5. The Al bonding wire according to any one of claims 1 to 4, wherein a wire diameter is 50 to 600 μm.